



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|---|
| Chip Size | 1812 |
| L | 4.52mm +/-0.3mm (0.178 in +/-0.012 in) |
| W | 3.2mm +/-0.3mm (0.126 in +/-0.012 in) |
| T | 2.79mm MAX (0.11 in MAX) |
| B | 0.61mm +/-0.46mm (0.024 in +/-0.018 in) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 42 |

General Information

| | |
|----------------|--|
| Series | SMD MIL COG PRF32535 |
| Style | SMD Chip |
| Description | SMD, Low ESR, MIL-PRF-32535 |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov . |
| SCIP Number | d66873f5-e54d-410c-a0cf-ebf6fc635b5 |
| Termination | Solder Plated |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 M-Level |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 0.1 uF |
| Capacitance Tolerance | 5% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | 0.25% 1 MHz 25C |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |